

Ranoda Technology, LLC

Board To Board Connector

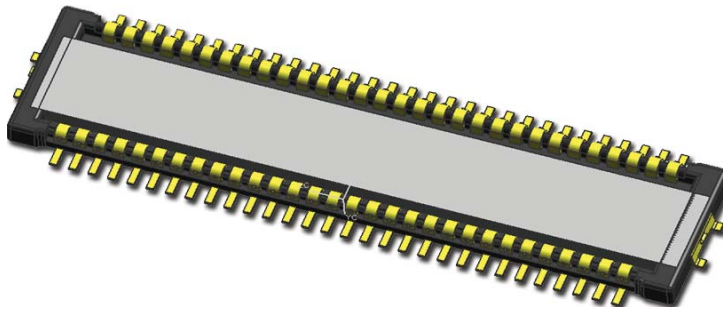
Mated Height 0.90mm

Contact spacing 0.40mm

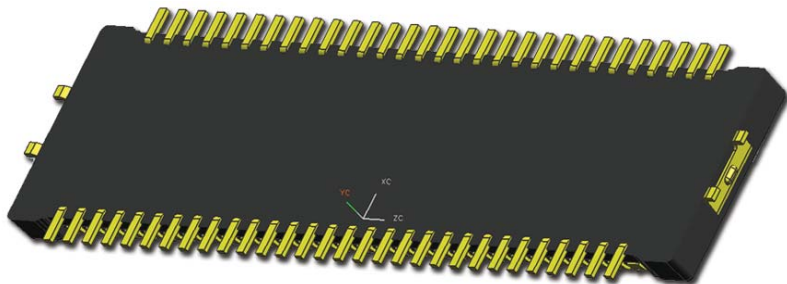
Insert Molded High Temp Insulator

Available in 60-80-100 Contact Count

Low Profile Board to Board Header



Low Profile Board to Board Socket



Low Profile Header

Header (Mated height: 0.9 mm)

dimension table(mm)

Dimensions Numberofcontacts	A	B	C
20	5.76	3.60	4.15
24	6.56	4.40	4.95
30	7.76	5.60	6.15
40	9.76	7.60	8.15
50	11.76	9.60	10.15
60	13.76	11.60	12.15
70	15.76	13.60	14.15
80	17.76	15.60	16.15

Mated drawing

Recommended PC board pattern

Material

Part name	Material
Molded portion	LCP resin(U94V-0)
Contact	Copper alloy

		Title	pitch 0.4mm mated height 0.9mm Board to Board connector	
Drawing	Material	Part no.	HYBH-**01A1	Rev. A
Checked	Drawing no.	Tolerance unless other wise spec.		
Approved	Approved	Unit	mm	General tolerance : ±0.2 Date:2011-03-28

Low Profile Socket

Socket (Mated height: 0.9 mm)

dimension table(mm)

Dimensions Numberofcontacts	A	B	C
20	6.60	3.60	5.76
24	7.40	4.40	6.56
30	8.60	5.60	7.76
40	10.60	7.60	9.76
50	12.60	9.60	11.76
60	14.60	11.60	13.76
70	16.60	13.60	15.76
80	18.60	15.60	17.76

Mated drawing

Recommended PC board pattern

Material

Part name	Material
Molded portion	LCP resin(U94V-0)
Contact	Copper alloy

		Title	pitch 0.4mm mated height 0.9mm Board to Board connector	
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